

DL4154

Small Signal Switching Diode

Features

- Fast Switching Speed and Low Current Leakage
- Compression Bond Construction and Low Cost
- Surface Mount Application
- Lead Free Finish/Rohs Compliant (Note1) ("P" Suffix designates Compliant. See ordering information)

Maximum Ratings

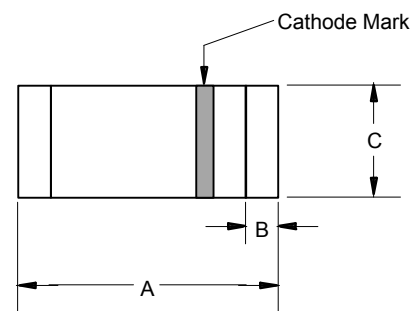
- Operation & Storage Temperature: -55°C to +150°C
- Maximum Thermal Resistance: 400k/W Junction to Ambient

Electrical Characteristics @ 25°C Unless Otherwise Specified

Reverse Voltage	V_R	25V	
Peak Reverse Voltage	V_{RM}	35V	
Average Rectified Current	I_O	150mA	Resistive Load $f > 50\text{Hz}$
Power Dissipation	P_{TOT}	500mW	
Junction Temperature	T_J	175°C	
Maximum Instantaneous Forward Volt.	V_F	1.0V	$I_{FM}=10\text{mA};$ $T_J=25^\circ\text{C}$
Maximum DC Reverse Current At Rated DC Blocking Volt.	I_R	0.1uA	$V_R=25\text{V}$ $T_J=25^\circ\text{C}$
Typical Junction Capacitance	C_J	4pF	Measured at 1.0MHz, $V_R=4.0\text{V}$
Reverse Recovery Time	T_{rr}	2nS	$I_F=10\text{mA}$ $V_R=6\text{V}$ $I_R=1\text{mA}$ $R_L=100\text{OHMS}$

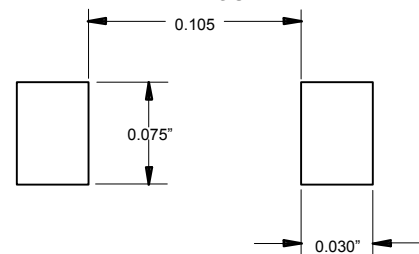
Note: 1. Lead in Glass Exemption Applied, see EU Directive Annex 5.

MINIMELF

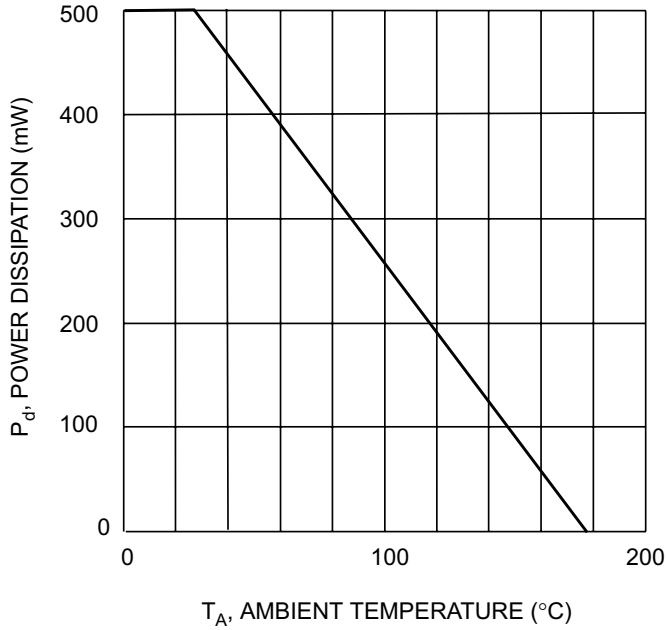


DIM	DIMENSION				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	.134	.142	3.40	3.60	
B	.008	.016	.20	.40	
C	.055	.059	1.40	1.50	

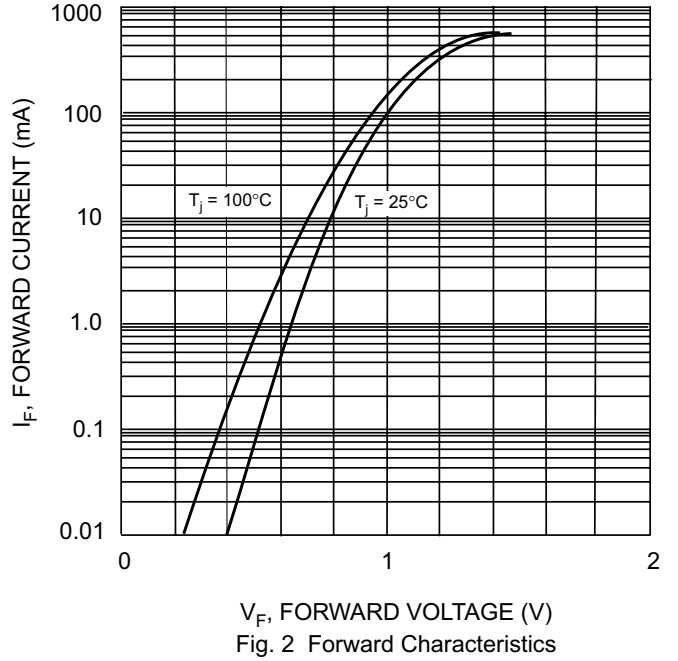
SUGGESTED SOLDER PAD LAYOUT



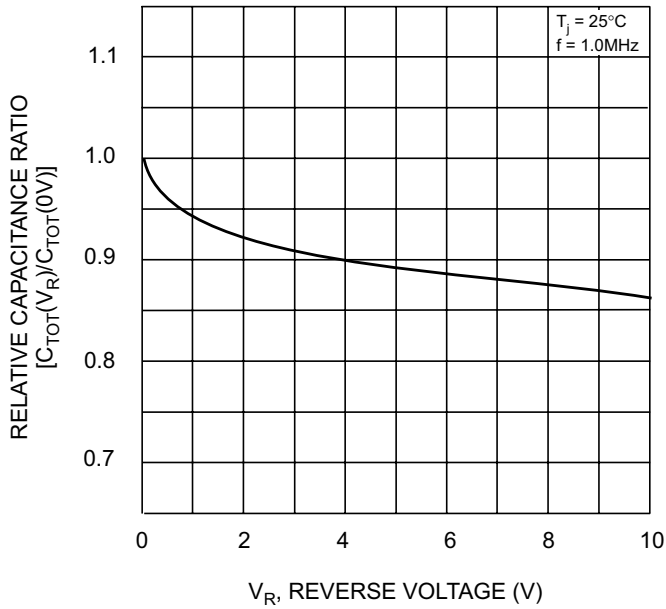
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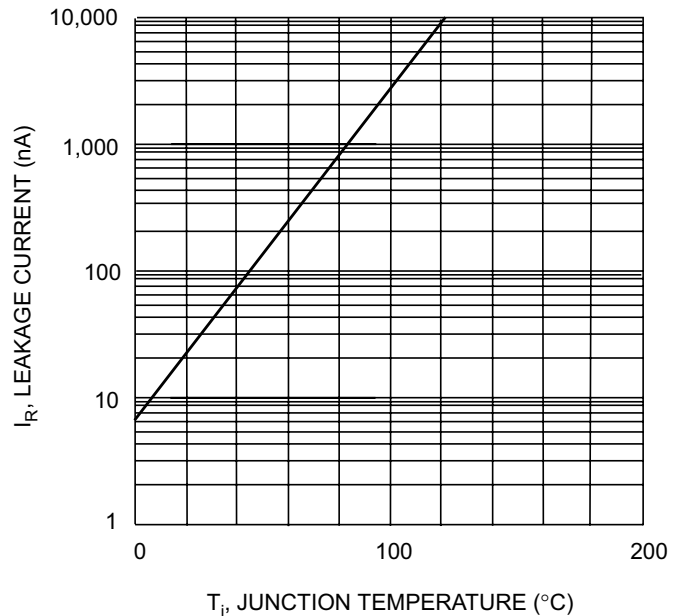
T_A , AMBIENT TEMPERATURE (°C)
Fig. 1 Power Derating Curve



V_F , FORWARD VOLTAGE (V)
Fig. 2 Forward Characteristics



V_R , REVERSE VOLTAGE (V)
Fig. 3 Relative Capacitance Variation



T_j , JUNCTION TEMPERATURE (°C)
Fig. 4 Leakage Current vs. Junction Temperature

Ordering Information

Device	Packing
(Part Number)-TP	Tape&Reel;2.5Kpcs/Reel